Zilog - Z8S18020FEC00TR Datasheet

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	Z8S180
Number of Cores/Bus Width	1 Core, 8-Bit
Speed	20MHz
Co-Processors/DSP	-
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	-40°C ~ 100°C (TA)
Security Features	-
Package / Case	80-BQFP
Supplier Device Package	80-QFP
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8s18020fec00tr

PIN IDENTIFICATION

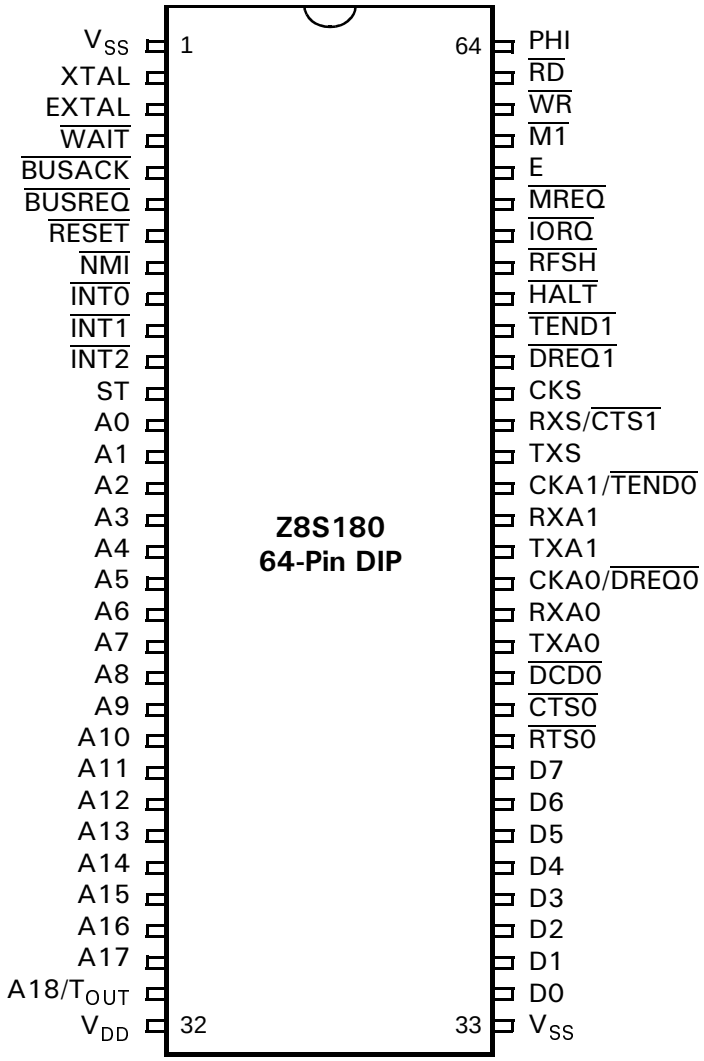


Figure 2. Z8S180 64-Pin DIP Pin Configuration

PIN IDENTIFICATION (Continued)

Table 1. Z8S180/Z8L180 Pin Identification (Continued)

Pin Number and Package Type			Default	Secondary	
QFP	PLCC	DIP	Function	Function	Control
13	19	17	A4		
14			NC		
15	20	18	A5		
16	21	19	A6		
17	22	20	A7		
18	23	21	A8		
19	24	22	A9		
20	25	23	A10		
21	26	24	A11		
22			NC		
23			NC		
24	27	25	A12		
25	28	26	A13		
26	29	27	A14		
27	30	28	A15		
28	31	29	A16		
29	32	30	A17		
30			NC		
31	33	31	A18	T_{OUT}	Bit 2 or Bit 3 of TCR
32	34	32	V_{DD}		
33	35		A19		
34	36	33	V_{SS}		
35	37	34	D0		
36	38	35	D1		
37	39	36	D2		
38	40	37	D3		
39	41	38	D4		
40	42	39	D5		
41	43	40	D6		
42			NC		
43			NC		
44	44	41	D7		
45	45	42	$\overline{RTS0}$		
46	46	43	$\overline{CTS0}$		
47	47	44	$\overline{DCD0}$		
48	48	45	TXA0		
49	49	46	RXA0		
50	50	47	CKA0	$\overline{DREQ0}$	Bit 3 or Bit 5 of DMODE
51			NC		
52	51	48	TXA1		

Table 2. Pin Status During RESET, BUSACK, and SLEEP Modes (Continued)

Pin Number and Package Type					Pin Status		
QFP	PLCC	DIP	Default Function	Secondary Function	RESET	BUSACK	SLEEP
39	41	38	D4		3T	3T	3T
40	42	39	D5		3T	3T	3T
41	43	40	D6		3T	3T	3T
42			NC				
43			NC				
44	44	41	D7		3T	3T	3T
45	45	42	$\overline{RTS0}$		High	OUT	High
46	46	43	$\overline{CTS0}$		IN	OUT	IN
47	47	44	$\overline{DCD0}$		IN	IN	IN
48	48	45	TXA0		High	OUT	OUT
49	49	46	RXA0		IN	IN	IN
50	50	47	CKA0		3T	I/O	I/O
			$\overline{DREQ0}$		N/A	IN	IN
51			NC				
52	51	48	TXA1		High	OUT	OUT
53	52		TEST				
54	53	49	RXA1		IN	IN	IN
55	54	50	CKA1		3T	I/O	I/O
			$\overline{TEND0}$		N/A	High	High
56	55	51	TXS		High	OUT	OUT
57	56	52	RXS		IN	IN	IN
			$\overline{CTS1}$		N/A	IN	IN
58	57	53	CKS		3T	I/O	I/O
59	58	54	$\overline{DREQ1}$		IN	3T	IN
60	59	55	$\overline{TEND1}$		High	OUT	High
61	60	56	$\overline{HALT}$		High	High	Low
62			NC				
63			NC				
64	61	57	$\overline{RFSH}$		High	OUT	High
65	62	58	$\overline{IORQ}$		High	3T	High
66	63	59	$\overline{MREQ}$		High	3T	High
67	64	60	E		Low	OUT	OUT
68	65	61	$\overline{M1}$		High	High	High
69	66	62	$\overline{WR}$		High	3T	High
70	67	63	$\overline{RD}$		High	3T	High
71	68	64	PHI		OUT	OUT	OUT
72	1	1	V_{SS}		GND	GND	GND
73	2		V_{SS}		GND	GND	GND
74	3	2	XTAL		OUT	OUT	OUT
75			NC				

PIN DESCRIPTIONS (Continued)

ways recognized at the end of an instruction, regardless of the state of the interrupt-enable flip-flops. This signal forces CPU execution to continue at location 0066H.

PHI. System Clock (Output). The output is used as a reference clock for the MPU and the external system. The frequency of this output may be one-half, equal to, or twice the crystal or input clock frequency.

$\overline{RD}$. Read (Output, active Low, 3-state). $\overline{RD}$ indicates that the CPU wants to read data from either memory or an I/O device. The addressed I/O or memory device should use this signal to gate data onto the CPU data bus.

$\overline{RFSH}$. Refresh (Output, active Low). Together with $\overline{MREQ}$, $\overline{RFSH}$ indicates that the current CPU machine cycle and the contents of the address bus should be used for refresh of dynamic memories. The low-order 8 bits of the address bus (A7–A0) contain the refresh address. *This signal is analogous to the $\overline{REF}$ signal of the Z64180.*

$\overline{RTS0}$. Request to Send 0 (Output, active Low); a programmable MODEM control signal for ASCI channel 0.

RXA0, RXA1. Receive Data 0 and 1 (Input). These signals are the receive data for the ASCI channels.

RXS. Clocked Serial Receive Data (Input). This line is the receive data for the CSI/O channel. RXS is multiplexed with the $\overline{CTS1}$ signal for ASCI channel 1.

ST. Status (Output). This signal is used with the $\overline{M1}$ and $\overline{HALT}$ output to decode the status of the CPU machine cycle. See Table 3.

Table 3. Status Summary

ST	$\overline{HALT}$	$\overline{M1}$	Operation
0	1	0	CPU Operation (1st Opcode Fetch)
1	1	0	CPU Operation (2nd Opcode and 3rd Opcode Fetch)
1	1	1	CPU Operation (MC Except Opcode Fetch)
0	X	1	DMA Operation
0	0	0	HALT Mode
1	0	1	SLEEP Mode (Including SYSTEM STOP Mode)

Notes:
X = Do not care.
MC = Machine Cycle.

$\overline{TEND0}$, $\overline{TEND1}$. Transfer End 0 and 1 (Outputs, active Low). This output is asserted active during the most recent WRITE cycle of a DMA operation. It is used to indicate the end of the block transfer. $\overline{TEND0}$ is multiplexed with CKA1.

TEST. Test (Output, not in DIP version). This pin is for test and should be left open.

T_{OUT}. Timer Out (Output). T_{OUT} is the output from PRT channel 1. This line is multiplexed with A18 of the address bus.

TXA0, TXA1. Transmit Data 0 and 1 (Outputs). These signals are the transmitted data from the ASCI channels. Transmitted data changes are with respect to the falling edge of the transmit clock.

TXS. Clocked Serial Transmit Data (Output). This line is the transmitted data from the CSI/O channel.

$\overline{WAIT}$. Wait (Input, active Low). $\overline{WAIT}$ indicates to the MPU that the addressed memory or I/O devices are not ready for data transfer. This input is sampled on the falling edge of T2 (and subsequent WAIT states). If the input is sampled Low, then the additional WAIT states are inserted until the $\overline{WAIT}$ input is sampled High, at which time execution continues.

$\overline{WR}$. WRITE (Output, active Low, 3-state). $\overline{WR}$ indicates that the CPU data bus holds valid data to be stored at the addressed I/O or memory location.

XTAL. Crystal Oscillator Connection (Input). This pin should be left open if an external clock is used instead of a crystal. The oscillator input is not a TTL level (see DC Characteristics).

Several pins are used for different conditions, depending on the circumstance.

ARCHITECTURE

The Z180 combines a high-performance CPU core with a variety of system and I/O resources useful in a broad range of applications. The CPU core consists of five functional blocks: clock generator, bus state controller, Interrupt controller, memory management unit (MMU), and the central processing unit (CPU). The integrated I/O resources make up the remaining four functional blocks: direct memory access (DMA) control (2 channels), asynchronous serial communication interface (ASCI, 2 channels) programmable reload timers (PRT, 2 channels), and a clock serial I/O (CSI/O) channel.

Clock Generator. This logic generates a system clock from an external crystal or clock input. The external clock is divided by 2 or 1 and provides the timing for both internal and external devices.

Bus State Controller. This logic performs all of the status and bus-control activity associated with the CPU and some on-chip peripherals. Also includes wait-state timing, reset cycles, DRAM refresh, and DMA bus exchanges.

Interrupt Controller. This logic monitors and prioritizes the variety of internal and external interrupts and traps to provide the correct responses from the CPU. To maintain compatibility with the Z80 CPU, three different interrupts modes are supported.

Memory Management Unit. The MMU allows the user to map the memory used by the CPU (logically only 64KB) into the 1-MB addressing range supported by the Z8S180/Z8L180. The organization of the MMU object code maintains compatibility with the Z80 CPU, while offering access to an extended memory space. Accomplished by using an effective common-area/banked-area scheme.

Central Processing Unit. The CPU is microcoded to provide a core that is object-code compatible with the Z80 CPU. It also provides a superset of the Z80 instruction set, including 8-bit multiplication. The core is modified to allow many of the instructions to execute in fewer clock cycles.

DMA Controller. The DMA controller provides high-speed transfers between memory and I/O devices. Transfer operations supported are memory-to-memory, memory to/from I/O, and I/O-to-I/O. Transfer modes supported are request, burst, and cycle steal. DMA transfers can access the full 1-MB address range with a block length up to 64 KB, and can cross over 64K boundaries.

Asynchronous Serial Communication Interface (ASCI).

The ASCI logic provides two individual full-duplex UARTs. Each channel includes a programmable baud rate generator and modem control signals. The ASCI channels can also support a multiprocessor communication format as well as break detection and generation

Programmable Reload Timers (PRT). This logic consists of two separate channels, each containing a 16-bit counter (timer) and count reload register. The time base for the counters is derived from the system clock (divided by 20) before reaching the counter. PRT channel 1 provides an optional output to allow for waveform generation.

OPERATION MODES

Z80 versus 64180 Compatibility. The Z8S180/Z8L180 is descended from two different "ancestor" processors, ZiLOG's original Z80 and the Hitachi 64180. The Operating Mode Control Register (OMCR), illustrated in Figure 8, can be programmed to select between certain Z80 and 64180 differences.

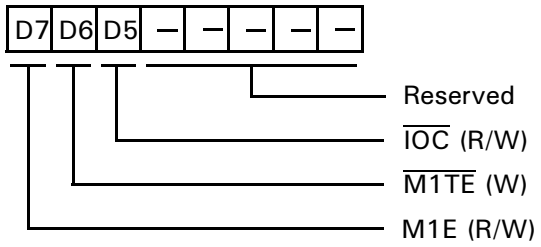


Figure 8. Operating Control Register (OMCR: I/O Address = 3EH)

M1E ($\overline{M1}$ Enable). This bit controls the $\overline{M1}$ output and is set to a 1 during RESET.

When M1E = 1, the $\overline{M1}$ output is asserted Low during opcode fetch cycles, Interrupt Acknowledge cycles, and the first machine cycle of an $\overline{NMI}$ acknowledge.

On the Z8S180/Z8L180, this choice makes the processor fetch a RETI instruction one time. When fetching a RETI from a zero-wait-state memory location, the processor uses three clock bus cycles. These bus cycles are not fully Z80-timing compatible.

When M1E = 0, the processor does not drive $\overline{M1}$ Low during the instruction fetch cycles. After fetching a RETI instruction with normal timing, the processor goes back and refetches the instruction using fully Z80-compatible cycles that include driving $\overline{M1}$ Low. This option may be required by some external Z80 peripherals to properly decode the RETI instruction. Figure 9 and Table 5 show the RETI sequence when M1E is 0.

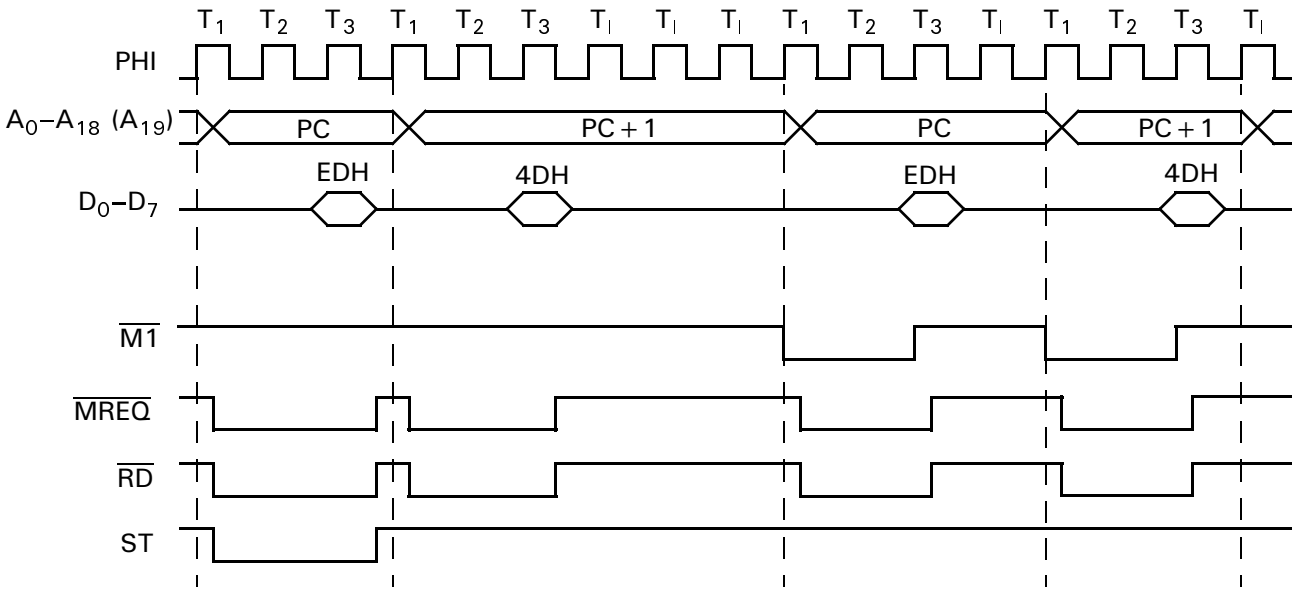


Figure 9. RETI Instruction Sequence with M1E = 0

STANDARD TEST CONDITIONS

The following standard test conditions apply to DC Characteristics, unless otherwise noted. All voltages are referenced to V_{SS} (0V). Positive current flows into the referenced pin.

All AC parameters assume a load capacitance of 100 pF. Add a 10-ns delay for each 50-pF increase in load up to a maximum of 200 pF for the data bus and 100 pF for the address and control lines. AC timing measurements are referenced to V_{OL} MAX or V_{OL} MIN as indicated in Figures 20 through 30 (except for CLOCK, which is referenced to the 10% and 90% points). Ordering Information lists temperature ranges and product numbers. Find package drawings in Package Information.

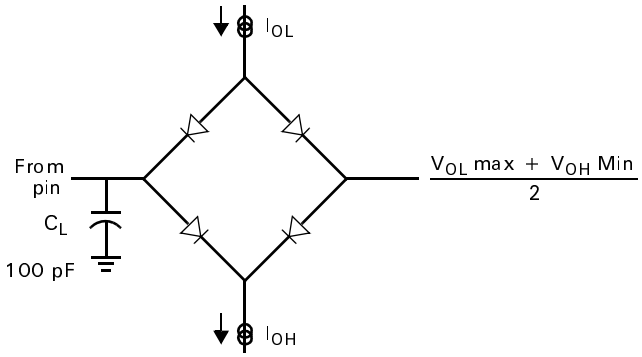


Figure 19. AC Parameter Test Circuit

ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V_{DD}	–0.3 ~ +7.0	V
Input Voltage	V_{IN}	–0.3 ~ V_{cc} +0.3	V
Operating Temperature	T_{OPR}	0 ~ 70	°C
Extended Temperature	T_{EXT}	–40 ~ 85	°C
Storage Temperature	T_{STG}	–55 ~ +150	°C

Note: Permanent damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability.

DC CHARACTERISTICS—Z8S180

Table 6. Z8S180 DC Characteristics
V_{DD} = 5V ±10%; V_{SS} = 0V

Symbol	Item	Condition	Min	Typ	Max	Unit
V_{IH1}	Input H Voltage $\overline{RESET}$, EXTAL, $\overline{NMI}$		V_{DD} –0.6	—	V_{DD} +0.3	V
V_{IH2}	Input H Voltage Except $\overline{RESET}$, EXTAL, $\overline{NMI}$		2.0	—	V_{DD} +0.3	V
V_{IH3}	Input H Voltage CKS, CKA0, CKA1		2.4	—	V_{DD} +0.3	V
V_{IL1}	Input L Voltage RESET, EXTAL, NMI		–0.3	—	0.6	V
V_{IL2}	Input L Voltage Except RESET, EXTAL, NMI		–0.3	—	0.8	V
V_{OH}	Outputs H Voltage All outputs	I_{OH} = –200 µA	2.4	—	—	V
		I_{OH} = –20 µA	V_{DD} –1.2	—	—	
V_{OL}	Outputs L Voltage All outputs	I_{OL} = 2.2 mA	—	—	0.45	V
I_{IL}	Input Leakage Current All Inputs Except XTAL, EXTAL	V_{IN} = 0.5 ~ V_{DD} –0.5	—	—	1.0	µA
I_{TL}	Three State Leakage Current	V_{IN} = 0.5 ~ V_{DD} –0.5	—	—	1.0	µA
I_{DD}[1]	Power Dissipation (Normal Operation)	F = 10 MHz	—	25	60	mA
		20		30	50	
		33		60	100	
	Power Dissipation (SYSTEM STOP mode)	F = 10 MHz	—	2	5	
		20		3	6	
		33		5	9	
C_P	Pin Capacitance	V_{IN} = 0_V, f = 1 MHz T_A = 25°C	—	—	12	pF

Note:
1. V_{IHmin} = V_{DD}–1.0V, V_{ILmax} = 0.8V (All output terminals are at NO LOAD.) V_{DD} = 5.0V.

AC CHARACTERISTICS—Z8S180

Table 8. Z8S180 AC Characteristics
V_{DD} = 5V ±10% or V_{DD} = 3.3V ±10%; 33-MHz Characteristics Apply Only to 5V Operation

			Z8S180—20 MHz		Z8S180—33 MHz		
Number	**Symbol**	**Item**	**Min**	**Max**	**Min**	**Max**	**Unit**
1	t_{CYC}	Clock Cycle Time	50	DC	30	DC	ns
2	t_{CHW}	Clock "H" Pulse Width	15	—	10	—	ns
3	t_{CLW}	Clock "L" Pulse Width	15	—	10	—	ns
4	t_{CF}	Clock Fall Time	—	10	—	5	ns
5	t_{CR}	Clock Rise Time	—	10	—	5	ns
6	t_{AD}	PHI Rise to Address Valid Delay	—	30	—	15	ns
7	t_{AS}	Address Valid to $\overline{MREQ}$ Fall or $\overline{IORQ}$ Fall)	5	—	5	—	ns
8	t_{MED1}	PHI Fall to $\overline{MREQ}$ Fall Delay	—	25	—	15	ns
9	t_{RDD1}	PHI Fall to $\overline{RD}$ Fall Delay $\overline{IOC}$ = 1	—	25	—	15	ns
		PHI Rise to $\overline{RD}$ Rise Delay $\overline{IOC}$ = 0	—	25	—	15	
10	t_{M1D1}	PHI Rise to $\overline{M1}$ Fall Delay	—	35	—	15	ns
11	t_{AH}	Address Hold Time from $\overline{MREQ}$, $\overline{IOREQ}$, $\overline{RD}$, $\overline{WR}$ High	5	—	5	—	ns
12	t_{MED2}	PHI Fall to $\overline{MREQ}$ Rise Delay	—	25	—	15	ns
13	t_{RDD2}	PHI Fall to $\overline{RD}$ Rise Delay	—	25	—	15	ns
14	t_{M1D2}	PHI Rise to $\overline{M1}$ Rise Delay	—	40	—	15	ns
15	t_{DRS}	Data Read Set-up Time	10	—	5	—	ns
16	t_{DRH}	Data Read Hold Time	0	—	0	—	ns
17	t_{STD1}	PHI Fall to ST Fall Delay	—	30	—	15	ns
18	t_{STD2}	PHI Fall to ST Rise Delay	—	30	—	15	ns
19	t_{WS}	$\overline{WAIT}$ Set-up Time to PHI Fall	15	—	10	—	ns
20	t_{WH}	$\overline{WAIT}$ Hold Time from PHI Fall	10	—	5	—	ns
21	t_{WDZ}	PHI Rise to Data Float Delay	—	35	—	20	ns
22	t_{WRD1}	PHI Rise to $\overline{WR}$ Fall Delay	—	25	—	15	ns
23	t_{WDD}	PHI Fall to Write Data Delay Time	—	25	—	15	ns
24	t_{WDS}	Write Data Set-up Time to $\overline{WR}$ Fall	10	—	10	—	ns
25	t_{WRD2}	PHI Fall to $\overline{WR}$ Rise Delay	—	25	—	15	ns
26	t_{WRP}	$\overline{WR}$ Pulse Width (Memory Write Cycle)	80	—	45	—	ns
26a		$\overline{WR}$ Pulse Width (I/O Write Cycle)	150	—	70	—	ns
27	t_{WDH}	Write Data Hold Time from $\overline{WR}$ Rise	10	—	5	—	ns
28	t_{IOD1}	PHI Fall to $\overline{IORQ}$ Fall Delay $\overline{IOC}$ = 1	—	25	—	15	ns
		PHI Rise to $\overline{IORQ}$ Fall Delay $\overline{IOC}$ = 0	—	25	—	15	
29	t_{IOD2}	PHI Fall to $\overline{IORQ}$ Rise Delay	—	25	—	15	ns
30	t_{IOD3}	$\overline{M1}$ Fall to $\overline{IORQ}$ Fall Delay	125	—	80	—	ns
31	t_{INTS}	$\overline{INT}$ Set-up Time to PHI Fall	20	—	15	—	ns

AC CHARACTERISTICS—Z8S180 (Continued)

Table 8. Z8S180 AC Characteristics (Continued)
V_{DD} = 5V ±10% or V_{DD} = 3.3V ±10%; 33-MHz Characteristics Apply Only to 5V Operation

			Z8S180—20 MHz		Z8S180—33 MHz		
Number	**Symbol**	**Item**	**Min**	**Max**	**Min**	**Max**	**Unit**
32	t_{INTH}	$\overline{INT}$ Hold Time from PHI Fall	10	—	10	—	ns
33	t_{NMIW}	$\overline{NMI}$ Pulse Width	35	—	25	—	ns
34	t_{BRS}	$\overline{BUSREQ}$ Set-up Time to PHI Fall	10	—	10	—	ns
35	t_{BRH}	$\overline{BUSREQ}$ Hold Time from PHI Fall	10	—	10		ns
36	t_{BAD1}	PHI Rise to $\overline{BUSACK}$ Fall Delay	—	25	—	15	ns
37	t_{BAD2}	PHI Fall to $\overline{BUSACK}$ Rise Delay	—	25	—	15	ns
38	t_{BZD}	PHI Rise to Bus Floating Delay Time	—	40	—	30	ns
39	t_{MEWH}	$\overline{MREQ}$ Pulse Width (High)	35	—	25	—	ns
40	t_{MEWL}	$\overline{MREQ}$ Pulse Width (Low)	35	—	25	—	ns
41	t_{RFD1}	PHI Rise to $\overline{RFSH}$ Fall Delay	—	20	—	15	ns
42	t_{RFD2}	PHI Rise to $\overline{RFSH}$ Rise Delay	—	20	—	15	ns
43	t_{HAD1}	PHI Rise to $\overline{HALT}$ Fall Delay	—	15	—	15	ns
44	t_{HAD2}	PHI Rise to $\overline{HALT}$ Rise Delay	—	15	—	15	ns
45	t_{DRQS}	$\overline{DREQ1}$ Set-up Time to PHI Rise	20	—	15	—	ns
46	t_{DRQH}	$\overline{DREQ1}$ Hold Time from PHI Rise	20	—	15	—	ns
47	t_{TED1}	PHI Fall to $\overline{TENDi}$ Fall Delay	—	25	—	15	ns
48	t_{TED2}	PHI Fall to $\overline{TENDi}$ Rise Delay	—	25	—	15	ns
49	t_{ED1}	PHI Rise to E Rise Delay	—	30	—	15	ns
50	t_{ED2}	PHI Fall or Rise to E Fall Delay	—	30	—	15	ns
51	P_{WEH}	E Pulse Width (High)	25	—	20	—	ns
52	P_{WEL}	E Pulse Width (Low)	50	—	40	—	ns
53	t_{Er}	Enable Rise Time	—	10	—	10	ns
54	t_{Ef}	Enable Fall Time	—	10	—	10	ns
55	t_{TOD}	PHI Fall to Timer Output Delay	—	75	—	50	ns
56	t_{STDI}	CSI/O Transmit Data Delay Time (Internal Clock Operation)	—	2	—	2	tcyc
57	t_{STDE}	CSI/O Transmit Data Delay Time (External Clock Operation)	—	7.5 t_{CYC} +75	—	75 t_{CYC} +60	ns
58	t_{SRSI}	CSI/O Receive Data Set-up Time (Internal Clock Operation)	1	—	1	—	tcyc
59	t_{SRHI}	CSI/O Receive Data Hold Time (Internal Clock Operation)	1	—	1	—	tcyc
60	t_{SRSE}	CSI/O Receive Data Set-up Time (External Clock Operation)	1	—	1	—	tcyc
61	t_{SRHE}	CSI/O Receive Data Hold Time (External Clock Operation)	1	—	1	—	tcyc
62	t_{RES}	$\overline{RESET}$ Set-up Time to PHI Fall	40	—	25	—	ns

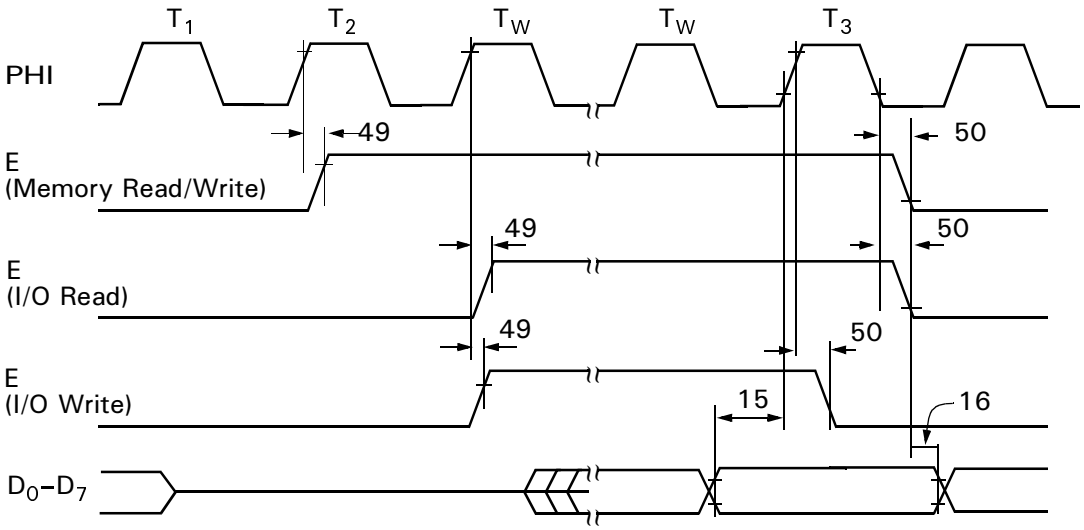


Figure 24. E Clock Timing
(Memory Read/Write Cycle, I/O Read/Write Cycle)

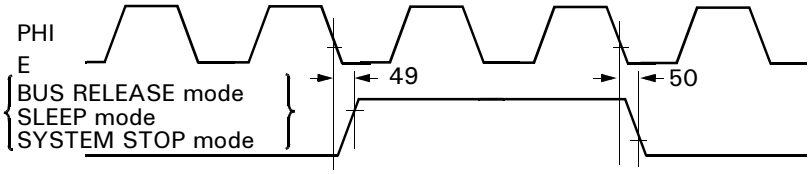


Figure 25. E Clock Timing
(BUS RELEASE Mode, SLEEP Mode, SYSTEM STOP Mode)

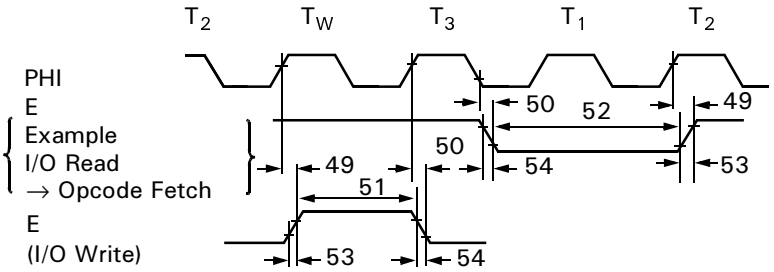


Figure 26. E Clock Timing
(Minimum Timing Example of P_{WEL} and P_{WEH})

ASCI RECEIVE REGISTER

Register addresses 08H and 09H hold the ASCI receive data for channel 0 and channel 1, respectively.

ASCI Receive Register Channel 0

Mnemonic RDR0
Address 08H

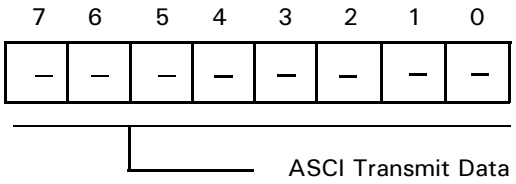


Figure 38. ASCI Receive Register Channel 0

ASCI Receive Register Channel 1

Mnemonic RDR1
Address 09H

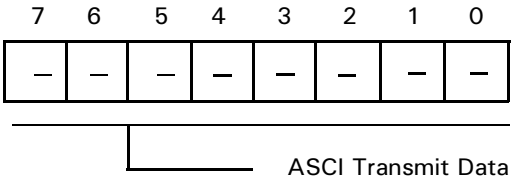


Figure 39. ASCI Receive Register Channel 1

CSI/O CONTROL/STATUS REGISTER

The CSI/O Control/Status Register (CNTR) is used to monitor CSI/O status, enable and disable the CSI/O, enable and disable interrupt generation, and select the data clock speed and source.

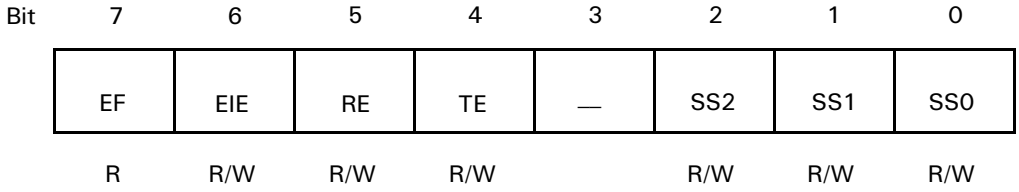


Figure 40. CSI/O Control Register (CNTR: I/O Address = 000AH)

EF: End Flag (Bit 7). EF is set to 1 by the CSI/O to indicate completion of an 8-bit data transmit or receive operation. If End Interrupt Enable (EIE) bit = 1 when EF is set to 1, a CPU interrupt request is generated. Program access of TRDR only occurs if EF = 1. The CSI/O clears EF to 0 when TRDR is read or written. EF is cleared to 0 during RESET and IOSTOP mode.

EIE: End Interrupt Enable (Bit 6). EIE is set to 1 to generate a CPU interrupt request. The interrupt request is inhibited if EIE is reset to 0. EIE is cleared to 0 during RESET.

RE: Receive Enable (Bit 5). A CSI/O receive operation is started by setting RE to 1. When RE is set to 1, the data clock is enabled. In internal clock mode, the data clock is output from the CKS pin. In external clock mode, the clock is input on the CKS pin. In either case, data is shifted in on the RXS pin in synchronization with the (internal or external) data clock. After receiving 8 bits of data, the CSI/O automatically clears RE to 0, EF is set to 1, and an interrupt (if enabled by EIE = 1) is generated. RE and TE are never both set to 1 at the same time. RE is cleared to 0 during RESET and IOSTOP mode.

TE: Transmit Enable (Bit 4). A CSI/O transmit operation is started by setting TE to 1. When TE is set to 1, the data clock is enabled. When in internal clock mode, the data clock is output from the CKS pin. In external clock mode, the clock is input on the CKS pin. In either case, data is shifted out on the TXS pin synchronous with the (internal or external) data clock. After transmitting 8 bits of data, the CSI/O automatically clears TE to 0, sets EF to 1, and requests an interrupt if enabled by EIE = 1. TE and RE are

never both set to 1 at the same time. TE is cleared to 0 during RESET and IOSTOP mode.

SS2, 1, 0: Speed Select 2, 1, 0 (Bits 2–0). SS2, SS1 and SS0 select the CSI/O transmit/receive clock source and speed. SS2, SS1 and SS0 are all set to 1 during $\overline{\text{RESET}}$. Table 11 indicates CSI/O Baud Rate Selection.

Table 11. CSI/O Baud Rate Selection

SS2	SS1	SS0	Divide Ratio
0	0	0	÷20
0	0	1	÷40
0	1	0	÷80
0	1	1	÷160
1	0	0	÷320
1	0	1	÷640
1	1	0	÷1280
1	1	1	External Clock Input (Less Than ÷20)

After $\overline{\text{RESET}}$, the CKS pin is configured as an external clock input (SS2, SS1, SS0 = 1). Changing these values causes CKS to become an output pin and the selected clock is output when transmit or receive operations are enabled.

CSI/O Transmit/Receive Data Register

Mnemonic TRDR
Address 0BH

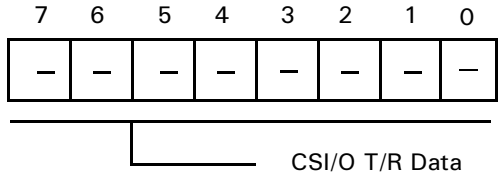


Figure 41. CSI/O Transmit/Receive Data Register

Timer Data Register Channel 0 Low

Mnemonic TMDR0L
Address 0CH

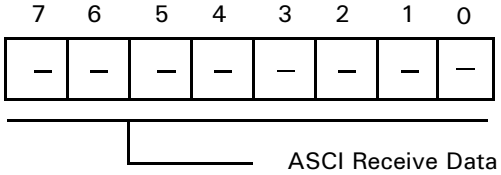


Figure 42. Timer Register Channel 0 Low

Timer Data Register Channel 0H

Mnemonic TMDR0H
Address 0DH

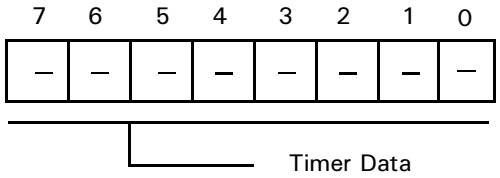


Figure 43. Timer Data Register Channel 0 High

Timer Reload Register Channel 0 Low

Mnemonic RLDR0L
Address 0EH

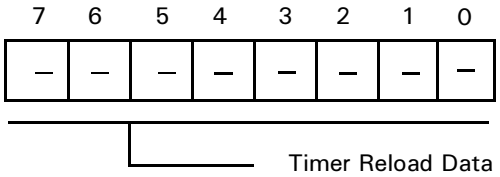


Figure 44. Timer Reload Register Low

Timer Reload Register Channel 0 High

Mnemonic RLDR0H
Address 0FH

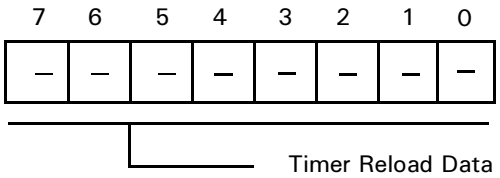


Figure 45. Timer Reload Register Channel 0 High

ASCI EXTENSION CONTROL REGISTER CHANNEL 0 AND CHANNEL 1

The ASCI Extension Control Registers (ASEXT0 and ASEXT1) control functions that have been added to the ASCIs in the Z8S180/Z8L180 family. All bits in this register reset to 0.

ASCI Extension Control Register 0 (ASEXT0 I/O Address = 12H)

Bit	7	6	5	4	3	2	1	0
	Reserved	DCD0 Disable	CTS0 Disable	X1	BRG0 Mode	Break Enable	Break	Send Break

ASCI Extension Control Register 1 (ASEXT1 I/O Address = 13H)

Bit	7	6	5	4	3	2	1	0
	Reserved	Reserved	Reserved	X1	BRG1 Mode	Break Enable	Break	Send Break

Figure 47. ASCI Extension Control Registers, Channels 0 and 1

DCD0 Disable (Bit 6, ASCI0 Only). If this bit is 0, then the $\overline{\text{DCD0}}$ pin auto-enables the ASCI0 receiver, such that when the pin is negated/High, the Receiver is held in a RESET state. If this bit is 1, the state of the $\overline{\text{DCD}}$-pin has no effect on receiver operation. In either state of this bit, software can read the state of the $\overline{\text{DCD0}}$ pin in the STAT0 register, and the receiver interrupts on a rising edge of $\overline{\text{DCD0}}$.

CTS0 Disable (Bit 5, ASCI0 Only). If this bit is 0, then the $\overline{\text{CTS0}}$ pin auto-enables the ASCIO transmitter, in that when the pin is negated/High, the TDRE bit in the STAT0 register is forced to 0. If this bit is 1, the state of the $\overline{\text{CTS0}}$ pin has no effect on the transmitter. Regardless of the state of this bit, software can read the state of the $\overline{\text{CTS0}}$ pin the CNTLB0 register.

X1 (Bit 4). If this bit is 1, the clock from the Baud Rate Generator or CKA pin is taken as a 1X-bit clock (sometimes called *isochronous mode*). In this mode, receive data on the RXA pin must be synchronized to the clock on the CKA pin, regardless of whether CKA is an input or an output. If this bit is 0, the clock from the Baud Rate Generator or CKA pin is divided by 16 or 64 per the DR bit in the CNTLB register, to obtain the actual bit rate. In this mode, receive data on the RXA pin is not required to be synchronized to a clock.

BRG Mode (Bit 3). If the SS2–0 bits in the CNTLB register are not 111, and this bit is 0, the ASCI Baud Rate Generator divides PHI by 10 or 30, depending on the PS bit in CNTLB, and factored by a power of two (selected by the SS2–0 bits), to obtain the clock that is presented to the transmitter and receiver and output on the CKA pin. If SS2–0 are not 111, and this bit is 1, the Baud Rate Generator divides PHI by twice the sum of the 16-bit value (programmed into the Time Constant registers) and 2. This mode is identical to the operation of the baud rate generator in the ESCC.

Break Enable (Bit 2). If this bit is 1, the receiver detects BREAK conditions and report them in bit 1, and the transmitter sends BREAKs under the control of bit 0.

Break Detect (Bit 1). The receiver sets this read-only bit to 1 when an all-zero character with a Framing Error becomes the oldest character in the Rx FIFO. The bit is cleared when software writes a 0 to the EFR bit in CNTLA register, also by RESET, by IOSTOP mode, and for ASCI0, if the $\overline{\text{DCD0}}$ pin is auto-enabled and is negated (High).

Send Break (Bit 0). If this bit and bit 2 are both 1, the transmitter holds the TXA pin Low to send a BREAK condition. The duration of the BREAK is under software control (one of the PRTs or CTCs can be used to time it). This bit resets to 0, in which state TXA carries the serial output of the transmitter.

ASCI TIME CONSTANT REGISTERS

If the SS2–0 bits of the CNTLB register are not 111, and the BRG mode bit in the ASEXT register is 1, the ASCI divides the PHI clock by two times the registers' 16-bit value, plus two. As a result, the clock is presented to the transmitter and receiver for division by 1, 16, or 64, and is output on the CKA pin.

If the SS2–0 bits in an ASCI CNTLB register are not 111, and the BRG mode bit in its Extension Control Register is 1, its *new* baud rate generator divides PHI for serial clocking, as follows:

$$\text{bits/second} = f_{PHI}/(2*(TC+2) \times \text{sampling rate})$$

where TC is the 16-bit value programmed into the ASCI Time Constant High and Low registers. If the ASCI multiplexed CKA pin is selected for the CKA function, it outputs the clock before the final division by the sampling rate, as follows:

$$f_{CKAout} = f_{PHI}/(2*(TC+2))$$

Find the TC value for a particular serial bit rate as follows:

$$TC = (f_{PHI}/(2 \times \text{bits/second} \times \text{sampling rate})) - 2$$

ASCI Time Constant Register 0 Low (ASTC0L, I/O Address 1AH)
ASCI Time Constant Register 1 Low (ASTC1L, I/O Address 1CH)

Bit	7	6	5	4	3	2	1	0
	LS 8 Bits of Time Constant							

ASCI Time Constant Register 0 High (ASTC0H, I/O Address 1BH)
ASCI Time Constant Register 1 High (ASTC1H, I/O Address 1DH)

Bit	7	6	5	4	3	2	1	0
	MS 8 Bits of Time Constant							

Figure 53. ASCI Time Constant Registers

DMA MEMORY ADDRESS REGISTER CHANNEL 1

The DMA Memory Address Register Channel 1 specifies the physical memory address for channel 1 transfers. The address may be a destination or a source memory location. The register contains 20 bits and may specify up to 1024 KB memory addresses.

DMA Memory Address Register, Channel 1L

Mnemonic MAR1L
Address 28H

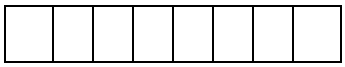


Figure 65. DMA Memory Address Register, Channel 1L

DMA Memory Address Register, Channel 1H

Mnemonic MAR1H
Address 29H

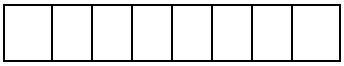


Figure 66. DMA Memory Address Register, Channel 1H

DMA Memory Address Register, Channel 1B

Mnemonic MAR1B
Address 2AH

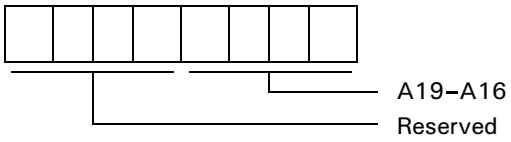


Figure 67. DMA Memory Address Register, Channel 1B

DMA I/O ADDRESS REGISTER

The DMA I/O Address Register specifies the I/O device for channel 1 transfers. This address may be a destination or source I/O device. IAR1L and IAR1H each contain 8 address bits. The most significant byte identifies the Request Handshake signal and controls the Alternating Channel feature.

DMA I/O Address Register Channel 1 Low

Mnemonic IAR1L
Address 2BH

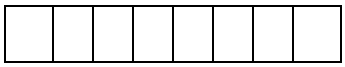


Figure 68. DMA I/O Address Register Channel 1 Low

DMA I/O Address Register Channel 1 High

Mnemonic IAR1H
Address 2CH

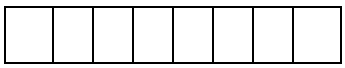


Figure 69. DMA I/O Address Register Channel 1 High

DMA I/O Address Register Channel 1 B

Mnemonic IAR1B
Address 2DH

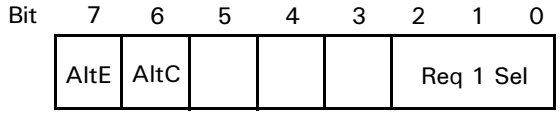


Figure 70. DMA I/O Address Register Channel 1 B

AltE. The AltE bit should be set only when both DMA channels are programmed for the same I/O source or I/O destination. In this case, a *channel end* condition (byte count = 0) on channel 0 sets bit 6 (AltC), which subsequently enables the channel 1 request and blocks the channel 0 request. Similarly, a channel end condition on channel 1 clears bit 6 (AltC), which then enables the channel 0 request and blocks the channel 1 request. For external requests, the request from the device must be routed or connected to both the DREQ0 and DREQ1 pins.

AltC. If bit (AltE) is 0, the AltC bit has no effect. When bit 7 (AltE) is 1 and the AltC bit is 0, the request signal selected by bits 2–0 is not presented to channel 1; however, the channel 0 request operates normally. When AltE is 1 and AltC is 1, the request selected by SAR18–16 or DAR18–16 is not presented to channel 0; however, the channel 1 request operates normally. The AltC bit can be written by software to select which channel should operate first; however, this operation should be executed only when both channels are stopped (both DE1 and DE0 are 0).

Req1Sel. If bit DIM1 in the DCNTL register is 1, indicating an I/O source, the following bits select which source handshake signal should control the transfer:

000	DREQ1 pin
001	ASCI0 RDRF
010	ASCI1 RDRF
Other	Reserved, do not program

If DIM1 is 0, indicating an I/O destination, the following bits select which destination handshake signal should control the transfer:

000	DREQ1 pin
001	ASCI0 TDRE
010	ASCI1 TDRE
Other	Reserved, do not program

Table 16 indicates all DMA transfer mode combinations of DM0, DM1, SM0, and SM1. Because I/O to/from I/O transfers are not implemented, 12 combinations are available.

Table 16. Transfer Mode Combinations

DM1	DM0	SM1	SM0	Transfer Mode	Address Increment/Decrement
0	0	0	0	Memory→Memory	SAR0 + 1, DAR0 + 1
0	0	0	1	Memory→Memory	SAR0–1, DAR0 + 1
0	0	1	0	Memory*→Memory	SAR0 fixed, DAR0 + 1
0	0	1	1	I/O→Memory	SAR0 fixed, DAR0 + 1
0	1	0	0	Memory→Memory	SAR0 + 1, DAR0–1
0	1	0	1	Memory→Memory	SAR0–1, DAR0–1
0	1	1	0	Memory*→Memory	SAR0 fixed, DAR0–1
0	1	1	1	I/O→Memory	SAR0 fixed, DAR0–1
1	0	0	0	Memory→Memory*	SAR0 + 1, DAR0 fixed
1	0	0	1	Memory→Memory*	SAR0–1, DAR0 fixed
1	0	1	0	Reserved	
1	0	1	1	Reserved	
1	1	0	0	Memory→I/O	SAR0 + 1, DAR0 fixed
1	1	0	1	Memory→I/O	SAR0–1, DAR0 fixed
1	1	1	0	Reserved	
1	1	1	1	Reserved	

Note: * Includes memory mapped I/O.

MMOD: Memory Mode Channel 0 (Bit 1). When channel 0 is configured for memory to/from memory transfers there is no Request Handshake signal to control the transfer timing. Instead, two automatic transfer timing modes are selectable: burst (MMOD = 1) and cycle steal (MMOD = 0). For burst memory to/from memory transfers, the DMAC takes control of the bus continuously until the DMA transfer completes (as indicated by the byte count register = 0). In cycle steal mode, the CPU is provided a cycle for each DMA byte transfer cycle until the transfer is completed.

For channel 0 DMA with I/O source or destination, the selected Request signal times the transfer ignoring MMOD. MMOD is cleared to 0 during RESET.

All TRAPs occur after fetching an undefined second opcode byte following one of the prefix opcodes (CBH, DDH, EDH, or FDH) or after fetching an undefined third opcode byte following one of the double-prefix opcodes (DDCBH or FDCBH).

The state of the Undefined Fetch Object (UFO) bit in ITC allows TRAP software to correctly *adjust* the stacked PC, depending on whether the second or third byte of the opcode generated the TRAP. If UFO = 0, the starting address of the invalid instruction is the stacked PC–1. If UFO = 1, the starting address of the invalid instruction is equal to the stacked PC–2.

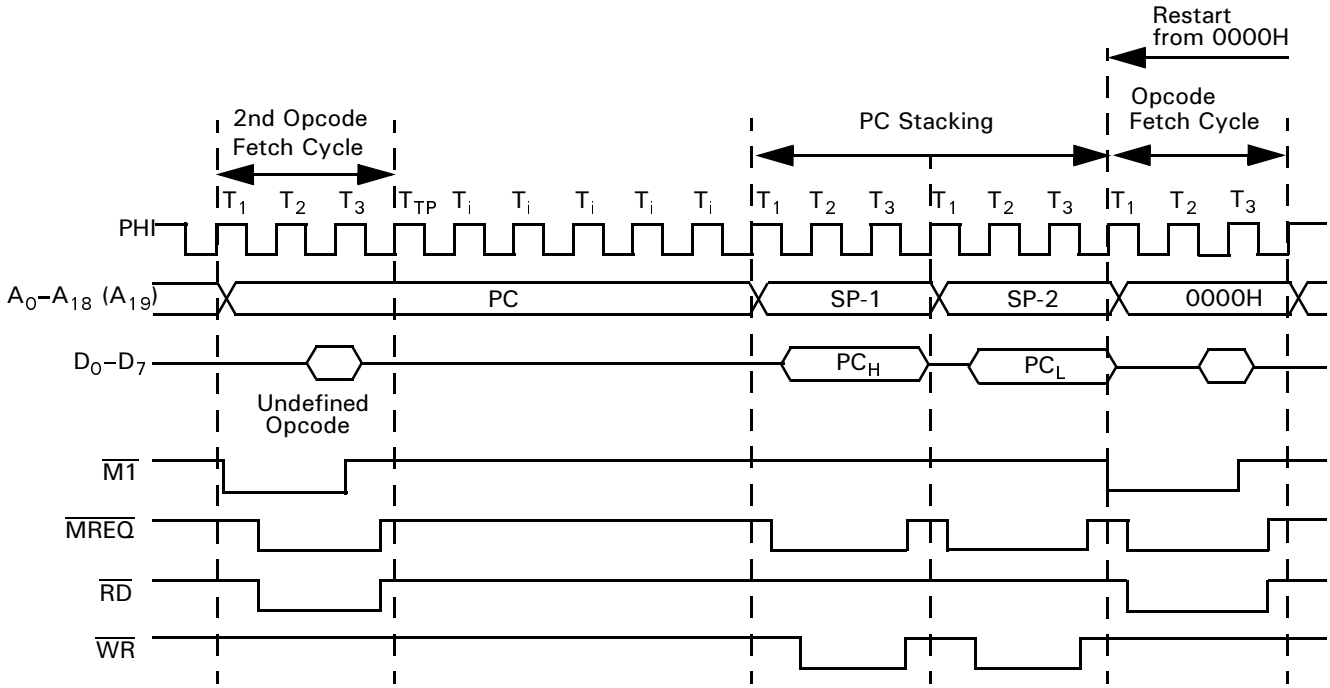
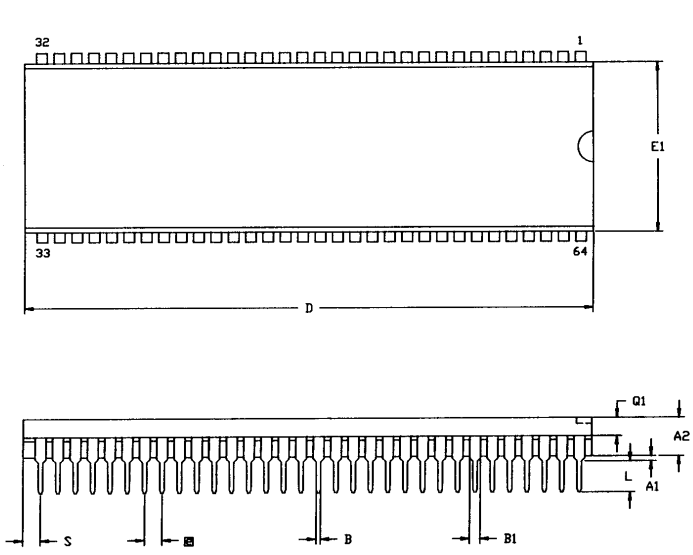


Figure 75. TRAP Timing—2nd Opcode Undefined

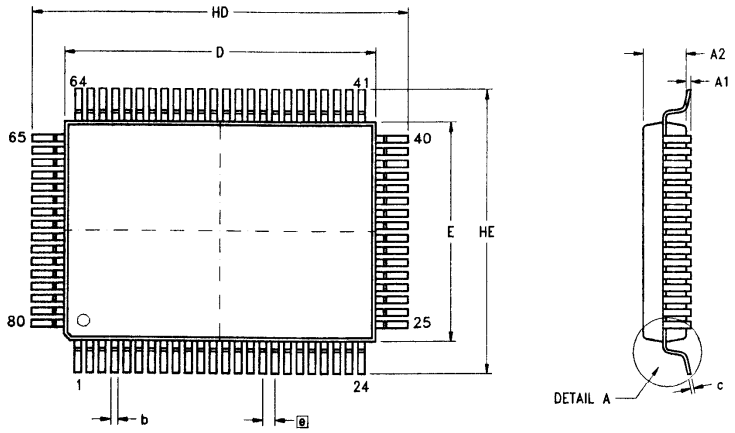
PACKAGE INFORMATION



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.38	1.07	.015	.042
A2	3.68	3.94	.145	.155
B	0.38	0.53	.015	.021
B1	0.94	1.09	.037	.043
C	0.23	0.38	.009	.015
D	57.40	58.17	2.260	2.290
E	18.80	19.30	.740	.760
E1	16.76	17.27	.660	.680
e	1.78 TYP		.070 TYP	
eA	19.30	20.32	.760	.800
L	3.18	3.81	.125	.150
Q1	1.65	1.91	.065	.075
S	1.02	1.78	.040	.070

CONTROLLING DIMENSIONS : INCH

Figure 85. 64-Pin DIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.10	0.30	.004	.012
A2	2.60	2.80	.102	.110
b	0.30	0.45	.012	.018
c	0.13	0.20	.005	.008
HD	23.70	24.15	.933	.951
D	19.90	20.10	.783	.791
HE	17.70	18.15	.697	.715
E	13.90	14.10	.547	.555
e	0.80 TYP		.0315 TYP	
L	0.70	1.10	.028	.043

NOTES:
1. CONTROLLING DIMENSIONS: MILLIMETER
2. MAX COPLANARITY: .10 / .004

Figure 86. 80-Pin QFP Package Diagram